

REMARKS

The present invention relates to a wiring substrate comprising a layer having an opening, at least one electronic part disposed in the opening, and an embedding resin.

The Examiner has not acknowledged Applicants' claim for foreign priority or indicated receipt of the certified copies of the priority documents. Applicants respectfully request that the Examiner make such an acknowledgement. Applicants herewith attach a copy of the PTO stamped filing receipt of March 8, 2002, which indicates that the certified copies of the priority documents were submitted on March 8, 2002.

The Examiner still has not acknowledged acceptance of the drawings filed on March 8, 2002. Applicants respectfully request that the Examiner acknowledge such an acceptance.

In the present Amendment, claims 5 and 6 have been amended to recite additional elements, i.e., an insulating layer covering the opening; a terminal electrode for mounting a semiconductor element, wherein the semiconductor element is on a surface of the wiring substrate; and via holes penetrating the insulating layer and connecting the terminal electrode to the embedded electronic part. This amendment is supported by the specification, for example, Figures 1 and 11.

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No new matter has been added, and thus entry of the present Amendment is respectfully submitted to be proper. Upon entry of the Amendment, claims 1-7, 9, 10 and 12 will be all the claims pending in the application.

At page 3 of the Office Action, claims 5-7, 9, 10 and 12 were rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Konarski (U.S. Pat. Appln. No. 2002/0058756) in view of Ichiroku et al (U.S. Pat. No. 6,117,953); at page 4 of the Office Action, the same claims were rejected based on Tsukagoshi et al (U.S. Pat. No. 5,120,665) in view of Ichiroku et al; lastly, at pages 4-5 of the Office Action, the same claims were rejected based on Sumita et al (U.S. Pat. No. 6,429,238) in view of Ichiroku et al.

Applicants respectfully submit that the present claims are not obvious over the cited references, and therefore the rejections should be withdrawn.

The resins disclosed in Ichiroku et al are underfilling materials used to fill a gap between an element on a surface of a substrate and the substrate. Therefore, it is impossible to apply the Ichiroku resins as an embedding resin. Accordingly, one of ordinary skill in the art would not be motivated to modify the embedding resins of the primary references with that of Ichiroku et al.

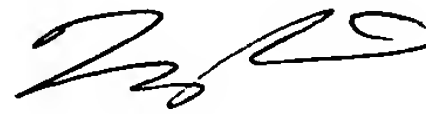
In view of the above, reconsideration and allowance of claims 1-7, 9, 10 and 12 are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which

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the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Fang Liu
Registration No. 51,283

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

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CUSTOMER NUMBER

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